L Number	Hits	Search Text	DB	Time stamp
1	96	(substrate) near3 (bonding or mounting or attachment or attaching) near3 (eutectic or eutectoid)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/24 08:53
8	1654	eutectoid	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/24 08:53
15	162	(substrate) near3 (bonding or mounting or attachment or attaching) near6 (eutectic or eutectoid)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/24 09:00
22	0	(substrate) near3 (bonding or mounting or attachment or attaching) near6 (eutectoid)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/24 08:53
29	11	(bonding or mounting or attachment or attaching) near6 (eutectoid)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/24 08:54
36	95	(substrate or die or chip or ic) near4 (bonding or mounting) and (adhesive or tape or epoxy) near4 (hole or perforation or cut or groove) near4 (vent or gas or air)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/24 09:08
-	118	(die or dice) near4 template near10 (aligning or alignment or align or positioning or position or positioned or aligned or placed or placement or arrangement or placing or arranging or arranged)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/22 15:14
-	10	((die or dice or ic or integrated adj circuit) near4 template near10 (aligning or alignment or align or positioning or position or positioned or aligned or placed or placement or arrangement or placing or arranging or arranged)) and (mems or micromirror or mirror)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 13:16
-	152	(die or dice or ic or integrated adj circuit) near4 template near10 (aligning or alignment or align or positioning or position or positioned or aligned or placed or placement or arrangement or placing or arranging or arranged)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 13:21
-	96	(ic or chip or die or integrated adj circuit) near4 template and substrate and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 14:29
-	733	(mems) and (die or dice or ic or mirror or micromirror) near3 (alignment or aligning or template or aligned or positioning or positioned or position or align or placement or location or locate or placing)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 14:42
-	2568	mems and template	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 14:42
-	211	mems and (mounting or mount or alignment or aligning or align or aligned or positioning or position) near8 template	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 14:46

-	44	mems! and (mounting or mount or alignment or aligning or align or aligned or positioning or position) near8 template	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 15:23
-	2	("5824186" | "6297072").PN.	USPAT	2003/01/13 15:17
-	125	mems! and (mounting or mount or alignment or aligning or align or aligned or positioning or position) near8 (substrate or wafer) near3 (recess or hole or divot or protrusion or projection or walls or indentation or indent)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 16:17
-	958	(alignment or aligning) near2 template	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 16:17
1	144	(mems and (mirror near2 arrays! or micromirror near2 arrays!)) and (bonding or placement or positioning or placing or mounting)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 13:50
8	152	moems	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 13:57
15	1	(bonding or mounting) near6 adhesive near4 (groove or cut or perforation or vent) near5 gas	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 14:00
22	7	(bonding or mounting) with adhesive near6 (groove or cut or perforation or vent) near5 gas	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 14:02
29	2348	(bonding or mounting) with substrate near6 (groove or cut or perforation or vent)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 14:03
36	37	(bonding or mounting) same substrate near6 (groove or cut or perforation or vent) near8 gas	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 14:09
43	858	(257/$.ccls. or 438/$.ccls.) and (mounting or bonding or adhering or bonded or mounted or adhesive or adhere) near4 (eutectic or eutectoid)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 14:17
-	2	(257/$.ccls. or 438/$.ccls.) and (mounting or bonding or adhering or bonded or mounted or adhesive or adhere) near4 (eutectic or eutectoid) near4 (parallel or tilt or flat or flattened or flatness or tilted)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 14:21
-	10	(257/$.ccls. or 438/$.ccls.) and (mounting or bonding or adhering or bonded or mounted or adhesive or adhere) near4 (eutectic or eutectoid) and (eutectic or cutectoid) near8 (parallel or tilt or flat or flattened or flatness or tilted or uniform or uniformity)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 15:52
-	858	(257/$.ccls. or 438/$.ccls.) and (mounting or bonding or adhering or bonded or mounted or adhesive or adhere) near4 (eutectic or eutectoid)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 15:54

-	108	(257/$.ccls. or 438/$.ccls.) and (mounting or bonding or adhering or bonded or mounted or adhesive or adhere) and (substrate or wafer) near2 (perforations or holes or vents or depressions or groove) near4 (gas or vent or venting or escape or escaping)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 16:02
-	19	(257/$.ccls. or 438/$.ccls.) and (mounting or bonding or adhering or bonded or mounted or adhesive or adhere) and (adhesive) near2 (perforations or holes or vents or depressions or groove) near4 (gas or vent or venting or escape or escaping)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/23 16:07

L Number	Hits	Search Text	DB	Time stamp
-	296	((alignment or aligning) near2 template) and (integrated adj circuit or ic or die or mems or mirror or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/13 16:19
-	17	die near3 (placing or placement or alignment) near4 template	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/22 15:16
-	432	die near3 (placing or placement or alignment or aligning) near4 (wall or protrusion or projection or hole or depression or concavity)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/22 16:14
-	2144	(chip or ic or wafer or substrate) near3 (placing or placement or alignment or aligning) near4 (template or wall or protrusion or projection or hole or depression or concavity)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/22 16:23
-	98	(chip or ic or wafer or substrate) near3 (placing or placement or alignment or aligning) near4 (template)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/22 16:37